



Material Content Data Sheet



Sales Product Name		ICE3BS03LJG		Issued		20. July 2018		
MA#		MA001039664						
Package		PG-DSO-8-42		Weight*		81.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.065	1.31	1.31	13060	13060
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.035	0.04		432	
	non noble metal	iron	7439-89-6	0.705	0.86		8643	
wire	non noble metal	copper	7440-50-8	28.624	35.09	36.00	350945	360128
	noble metal	gold	7440-57-5	0.171	0.21	0.21	2100	2100
	encapsulation	organic material	carbon black	1333-86-4	0.148	0.18		1819
plastics	plastics	epoxy resin	-	4.798	5.88		58822	
	inorganic material	silicondioxide	60676-86-0	44.514	54.60	60.66	545775	606416
leadfinish	non noble metal	tin	7440-31-5	0.824	1.01	1.01	10103	10103
plating	noble metal	silver	7440-22-4	0.084	0.10	0.10	1034	1034
glue	plastics	acrylic resin	-	0.117	0.14		1432	
	noble metal	silver	7440-22-4	0.467	0.57	0.71	5727	7159
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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